AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph on page 1, line 26, to page 2, line 11, as follows:

The high accuracy metrology of test specimens, such as the topographic measurement of bow, warp, flatness, thickness etc. of such objects as semiconductor wafers, magnetic disks and the like, is impeded by the presence of noise in the output data. Depending on the inherent properties of the instrument and the environment, the data may have a noise content that displays larger peak to peak magnitude ~~that~~ than the actual dimensions being measured. It is difficult to remove all sources of wafer vibration in a sensor based dimensional metrology system when the wafer moves between the sensors. The natural frequency of wafer vibration is of the order of tens to a few hundred Hertz, depending on wafer size and loading conditions, and the observed pattern of vibration has a spatial wavelength less than a few mm. If this noise is not removed, it directly affects the repeatability and reproducibility of the measurements of the system.

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